

# Ultra High Speed Switching Diodes

## HN2D02FUTW1T1G, SHN2D02FUTW1T1G

These Silicon Epitaxial Planar Diodes are designed for use in ultra high speed switching applications. These devices are housed in the SC-88 package which is designed for low power surface mount applications.

### Features

- Fast  $t_{rr}$ , < 3.0 ns
- Low  $C_D$ , < 2.0 pF
- AEC-Q101 Qualified and PPAP Capable
- S Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements
- These Devices are Pb-Free, Halogen Free/BFR Free and are RoHS Compliant\*

### MAXIMUM RATINGS ( $T_A = 25^\circ\text{C}$ )

| Rating                                      | Symbol    | Value | Unit |
|---------------------------------------------|-----------|-------|------|
| Reverse Voltage                             | $V_R$     | 80    | V    |
| Peak Reverse Voltage                        | $V_{RM}$  | 85    | V    |
| Forward Current (Note 1)                    | $I_F$     | 100   | mAdc |
| Peak Forward Current (Note 1)               | $I_{FM}$  | 240   | mAdc |
| Peak Forward Surge Current (10 ms) (Note 1) | $I_{FSM}$ | 1.0   | Adc  |

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

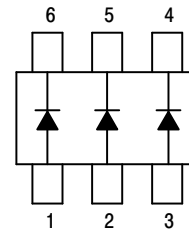
- This is maximum rating for a single diode. In the case of using 2 or 3 diodes, the maximum ratings per diodes is 75% of the single diode.

### THERMAL CHARACTERISTICS

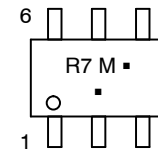
| Rating               | Symbol    | Max         | Unit             |
|----------------------|-----------|-------------|------------------|
| Power Dissipation    | $P_D$     | 300         | mW               |
| Junction Temperature | $T_J$     | 150         | $^\circ\text{C}$ |
| Storage Temperature  | $T_{stg}$ | -55 to +150 | $^\circ\text{C}$ |



SC-88  
CASE 419B-02  
STYLE 1



### MARKING DIAGRAM



- R7 = Specific Device Code  
M = Date Code  
▪ = Pb-Free Package

(Note: Microdot may be in either location)

### ORDERING INFORMATION

| Device          | Package            | Shipping†             |
|-----------------|--------------------|-----------------------|
| HN2D02FUTW1T1G  | SC-88<br>(Pb-Free) | 3000 /<br>Tape & Reel |
| SHN2D02FUTW1T1G | SC-88<br>(Pb-Free) | 3000 /<br>Tape & Reel |

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specification Brochure, [BRD8011/D](#).

\*For additional information on our Pb-Free strategy and soldering details, please download the [onsemi Soldering and Mounting Techniques Reference Manual, SOLDERRM/D](#).

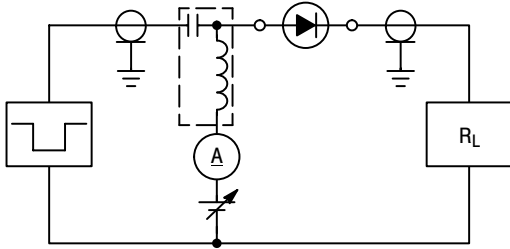
# HN2D02FUTW1T1G, SHN2D02FUTW1T1G

## ELECTRICAL CHARACTERISTICS ( $T_A = 25^\circ\text{C}$ )

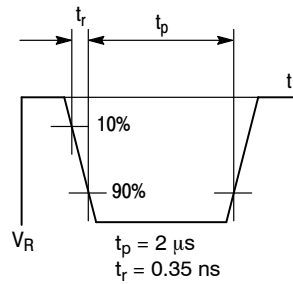
| Characteristic                   | Symbol            | Condition                                                                           | Min | Max | Unit                      |
|----------------------------------|-------------------|-------------------------------------------------------------------------------------|-----|-----|---------------------------|
| Reverse Voltage Leakage Current  | $I_R$             | $V_R = 30\text{ V}$                                                                 | –   | 0.1 | $\mu\text{A}_{\text{dc}}$ |
|                                  |                   | $V_R = 80\text{ V}$                                                                 | –   | 0.5 |                           |
| Forward Voltage                  | $V_F$             | $I_F = 100\text{ mA}$                                                               | –   | 1.2 | $\text{V}_{\text{dc}}$    |
| Reverse Breakdown Voltage        | $V_R$             | $I_R = 100\text{ }\mu\text{A}$                                                      | 80  | –   | $\text{V}_{\text{dc}}$    |
| Diode Capacitance                | $C_D$             | $V_R = 0, f = 1.0\text{ MHz}$                                                       | –   | 2.0 | $\text{pF}$               |
| Reverse Recovery Time (Figure 1) | $t_{rr}$ (Note 2) | $I_F = 10\text{ mA}, V_R = 6.0\text{ V}, R_L = 100\text{ }\Omega, I_{rr} = 0.1 I_F$ | –   | 3.0 | $\text{ns}$               |

2.  $t_{rr}$  Test Circuit

### RECOVERY TIME EQUIVALENT TEST CIRCUIT



### INPUT PULSE



### OUTPUT PULSE

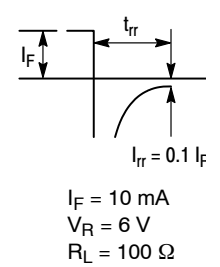


Figure 1. Reverse Recovery Time Equivalent Test Circuit

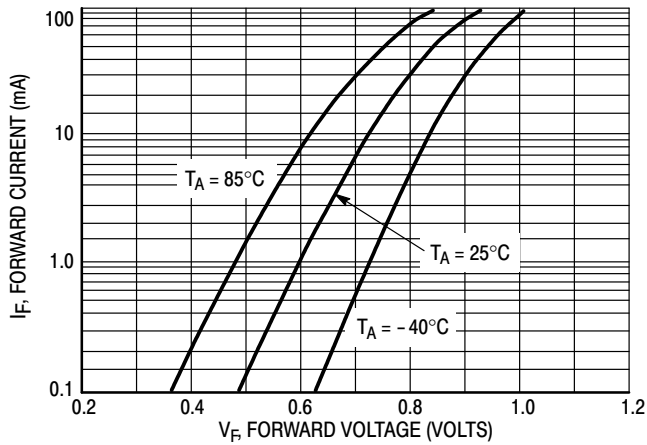


Figure 2. Forward Voltage

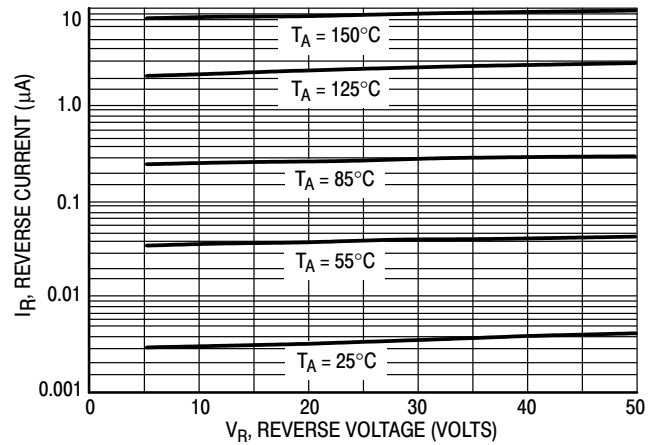


Figure 3. Leakage Current

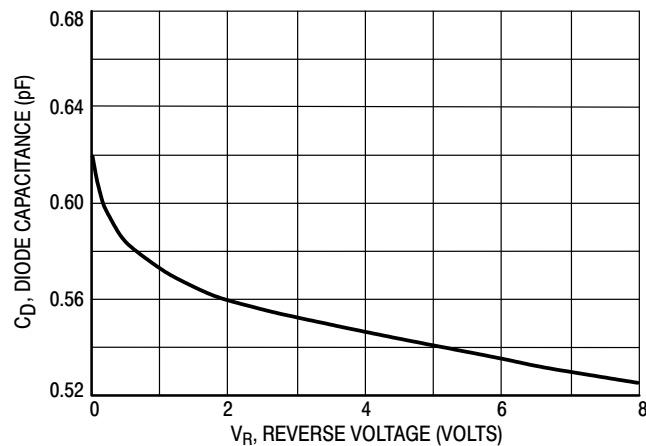


Figure 4. Capacitance

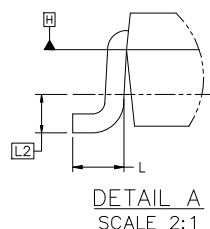
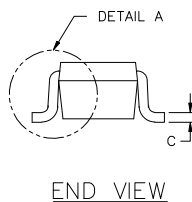
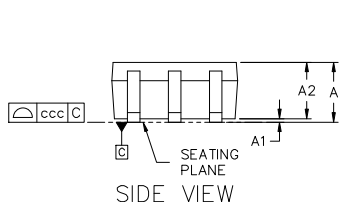
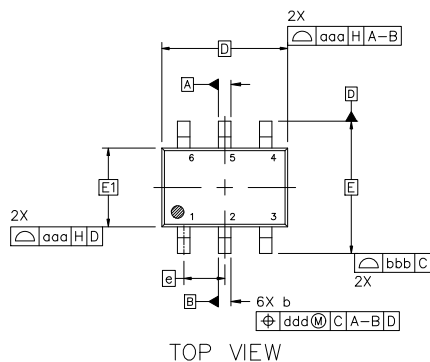


SC-88 2.00x1.25x0.90, 0.65P  
CASE 419B-02  
ISSUE Z

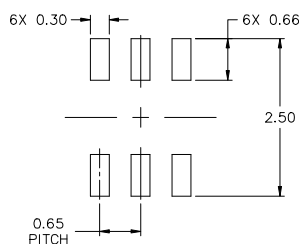
DATE 18 APR 2024

NOTES:

1. DIMENSIONING AND TOLERANCING CONFORM TO ASME Y14.5-2018.
2. ALL DIMENSION ARE IN MILLIMETERS.
3. DIMENSIONS D AND E1 DO NOT INCLUDE MOLD FLASH, PROTRUSIONS, OR GATE BURRS. MOLD FLASH, PROTRUSIONS, OR GATE BURRS SHALL NOT EXCEED 0.20 PER END.
4. DIMENSIONS D AND E1 AT THE OUTERMOST EXTREMES OF THE PLASTIC BODY AND DATUM H.
5. DATUMS A AND B ARE DETERMINED AT DATUM H.
6. DIMENSIONS b AND c APPLY TO THE FLAT SECTION OF THE LEAD BETWEEN 0.08 AND 0.15 FROM THE TIP.
7. DIMENSION b DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.08 TOTAL IN EXCESS OF DIMENSION b AT MAXIMUM MATERIAL CONDITION. THE DAMBAR CANNOT BE LOCATED ON THE LOWER RADIUS OF THE FOOT.



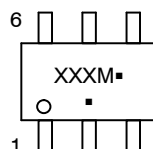
| DIM | MILLIMETERS |      |      |
|-----|-------------|------|------|
|     | MIN.        | NOM. | MAX. |
| A   | ---         | ---  | 1.10 |
| A1  | 0.00        | ---  | 0.10 |
| A2  | 0.70        | 0.90 | 1.00 |
| b   | 0.15        | 0.20 | 0.25 |
| c   | 0.08        | 0.15 | 0.22 |
| D   | 2.00 BSC    |      |      |
| E   | 2.10 BSC    |      |      |
| E1  | 1.25 BSC    |      |      |
| e   | 0.65 BSC    |      |      |
| L   | 0.26        | 0.36 | 0.46 |
| L2  | 0.15 BSC    |      |      |
| aaa | 0.15        |      |      |
| bbb | 0.30        |      |      |
| ccc | 0.10        |      |      |
| ddd | 0.10        |      |      |



RECOMMENDED MOUNTING FOOTPRINT\*

\* FOR ADDITIONAL INFORMATION ON OUR Pb-FREE STRATEGY AND SOLDERING DETAILS, PLEASE DOWNLOAD THE ONSEMI SOLDERING AND MOUNTING TECHNIQUES REFERENCE MANUAL, SOLDERRM/D.

GENERIC  
MARKING DIAGRAM\*



XXX = Specific Device Code  
M = Date Code\*  
▪ = Pb-Free Package

(Note: Microdot may be in either location)

\*Date Code orientation and/or position may vary depending upon manufacturing location.

\*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "▪", may or may not be present. Some products may not follow the Generic Marking.

STYLES ON PAGE 2

|                  |                             |                                                                                                                                                                                  |
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SC-88 2.00x1.25x0.90, 0.65P  
CASE 419B-02  
ISSUE Z

DATE 18 APR 2024

|                                                                                                            |                                                                                                        |                                                                                                             |                                                                                                             |                                                                                                             |                                                                                                       |
|------------------------------------------------------------------------------------------------------------|--------------------------------------------------------------------------------------------------------|-------------------------------------------------------------------------------------------------------------|-------------------------------------------------------------------------------------------------------------|-------------------------------------------------------------------------------------------------------------|-------------------------------------------------------------------------------------------------------|
| STYLE 1:<br>PIN 1. EMITTER 2<br>2. BASE 2<br>3. COLLECTOR 1<br>4. EMITTER 1<br>5. BASE 1<br>6. COLLECTOR 2 | STYLE 2:<br>CANCELLED                                                                                  | STYLE 3:<br>CANCELLED                                                                                       | STYLE 4:<br>PIN 1. CATHODE<br>2. CATHODE<br>3. COLLECTOR<br>4. EMITTER<br>5. BASE<br>6. ANODE               | STYLE 5:<br>PIN 1. ANODE<br>2. ANODE<br>3. COLLECTOR<br>4. EMITTER<br>5. BASE<br>6. CATHODE                 | STYLE 6:<br>PIN 1. ANODE 2<br>2. N/C<br>3. CATHODE 1<br>4. ANODE 1<br>5. N/C<br>6. CATHODE 2          |
| STYLE 7:<br>PIN 1. SOURCE 2<br>2. DRAIN 2<br>3. GATE 1<br>4. SOURCE 1<br>5. DRAIN 1<br>6. GATE 2           | STYLE 8:<br>CANCELLED                                                                                  | STYLE 9:<br>PIN 1. EMITTER 2<br>2. EMITTER 1<br>3. COLLECTOR 1<br>4. BASE 1<br>5. BASE 2<br>6. COLLECTOR 2  | STYLE 10:<br>PIN 1. SOURCE 2<br>2. SOURCE 1<br>3. GATE 1<br>4. DRAIN 1<br>5. DRAIN 2<br>6. GATE 2           | STYLE 11:<br>PIN 1. CATHODE 2<br>2. CATHODE 2<br>3. ANODE 1<br>4. CATHODE 1<br>5. CATHODE 1<br>6. ANODE 2   | STYLE 12:<br>PIN 1. ANODE 2<br>2. ANODE 2<br>3. CATHODE 1<br>4. ANODE 1<br>5. ANODE 1<br>6. CATHODE 2 |
| STYLE 13:<br>PIN 1. ANODE<br>2. N/C<br>3. COLLECTOR<br>4. EMITTER<br>5. BASE<br>6. CATHODE                 | STYLE 14:<br>PIN 1. VREF<br>2. GND<br>3. GND<br>4. IOUT<br>5. VEN<br>6. VCC                            | STYLE 15:<br>PIN 1. ANODE 1<br>2. ANODE 2<br>3. ANODE 3<br>4. CATHODE 3<br>5. CATHODE 2<br>6. CATHODE 1     | STYLE 16:<br>PIN 1. BASE 1<br>2. EMITTER 2<br>3. COLLECTOR 2<br>4. BASE 2<br>5. EMITTER 1<br>6. COLLECTOR 1 | STYLE 17:<br>PIN 1. BASE 1<br>2. EMITTER 1<br>3. COLLECTOR 2<br>4. BASE 2<br>5. EMITTER 2<br>6. COLLECTOR 1 | STYLE 18:<br>PIN 1. VIN1<br>2. VCC<br>3. VOUT2<br>4. VIN2<br>5. GND<br>6. VOUT1                       |
| STYLE 19:<br>PIN 1. I OUT<br>2. GND<br>3. GND<br>4. V CC<br>5. V EN<br>6. V REF                            | STYLE 20:<br>PIN 1. COLLECTOR<br>2. COLLECTOR<br>3. BASE<br>4. EMITTER<br>5. COLLECTOR<br>6. COLLECTOR | STYLE 21:<br>PIN 1. ANODE 1<br>2. N/C<br>3. ANODE 2<br>4. CATHODE 2<br>5. N/C<br>6. CATHODE 1               | STYLE 22:<br>PIN 1. D1 (i)<br>2. GND<br>3. D2 (i)<br>4. D2 (c)<br>5. VBUS<br>6. D1 (c)                      | STYLE 23:<br>PIN 1. Vn<br>2. CH1<br>3. Vp<br>4. N/C<br>5. CH2<br>6. N/C                                     | STYLE 24:<br>PIN 1. CATHODE<br>2. ANODE<br>3. CATHODE<br>4. CATHODE<br>5. CATHODE<br>6. CATHODE       |
| STYLE 25:<br>PIN 1. BASE 1<br>2. CATHODE<br>3. COLLECTOR 2<br>4. BASE 2<br>5. EMITTER<br>6. COLLECTOR 1    | STYLE 26:<br>PIN 1. SOURCE 1<br>2. GATE 1<br>3. DRAIN 2<br>4. SOURCE 2<br>5. GATE 2<br>6. DRAIN 1      | STYLE 27:<br>PIN 1. BASE 2<br>2. BASE 1<br>3. COLLECTOR 1<br>4. EMITTER 1<br>5. EMITTER 2<br>6. COLLECTOR 2 | STYLE 28:<br>PIN 1. DRAIN<br>2. DRAIN<br>3. GATE<br>4. SOURCE<br>5. DRAIN<br>6. DRAIN                       | STYLE 29:<br>PIN 1. ANODE<br>2. ANODE<br>3. COLLECTOR<br>4. EMITTER<br>5. BASE/ANODE<br>6. CATHODE          | STYLE 30:<br>PIN 1. SOURCE 1<br>2. DRAIN 2<br>3. DRAIN 2<br>4. SOURCE 2<br>5. GATE 1<br>6. DRAIN 1    |

Note: Please refer to datasheet for style callout. If style type is not called out in the datasheet refer to the device datasheet pinout or pin assignment.

|                  |                             |                                                                                                                                                                                     |
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